

*Amend*  
09110527-070698  
continuation of United States Patent Application No. 08/030,194, filed April 28, 1993 as the national phase of International Application PCT/US91/06920 filed September 24, 1991. Said 08/030,194 application, now United States Patent No. 5,679,977, was in turn a continuation of United States Patent Application No. 07/765,928, filed September 24, 1991, now United States Patent No. 5,347,159. Said United States Patent Application No. 07/765,928 was a continuation in part of United States Patent Application No. 07/673,020, filed March 21, 1991, now United States Patent No. 5,148,265 and said United States Patent Application No. 07/765,928 was a continuation in part of United States Patent Application No. 07/586,758, filed September 24, 1990, now United States Patent No. 5,148,266. Said United States Patent Application No. 08/030,194 is also a continuation in part of said United States Patent Application Nos. 07/586,758 and 07/673,020.

Page 1, line 9, delete "TECHNICAL FIELD" and insert  
-- BACKGROUND OF THE INVENTION --.

Page 6, line 9, change "sulder" to -- solder --.

Page 12, line 24, change "thermolcompression" to  
-- thermocompression --.

Page 33, line 23, change "centerto-center" to -- center-to-center --.

**In the Abstract:**

Please cancel the abstract presently on file and substitute therefor the  
following: -- ABSTRACT OF THE DISCLOSURE

*Advent*  
6-5  
A semiconductor assembly having contacts on a peripheral region of the top surface of a chip and a backing element overlying the bottom surface of the chip. The backing element has terminals such that at least some of the